

ABSTRACT OF THE DISCLOSURE

5 A technique for electrically interconnecting a signal
between a first circuit board and a second circuit board is
disclosed. In each board, at least one signal conductor is
shielded by an electrically conductive shield. Multiple
conductors may be shielded by the same shield. A first
opening is formed in the electrically conductive shield of
the first circuit board and a second opening is formed in
10 the electrically conductive shield of the second circuit
board so as to expose the signal conductor in the each
circuit board. An electrically conductive adhesive, reflowed
solder paste, or interposer/elastomer device is applied
surrounding at least one of the openings and may further be
15 applied within at least one of the openings. The first
circuit board and the second circuit board are then
positioned such that the first opening and the second
opening are aligned and a signal propagating along the first
signal conductor is electrically interconnected to the
20 second signal conductor.

09749409-122800